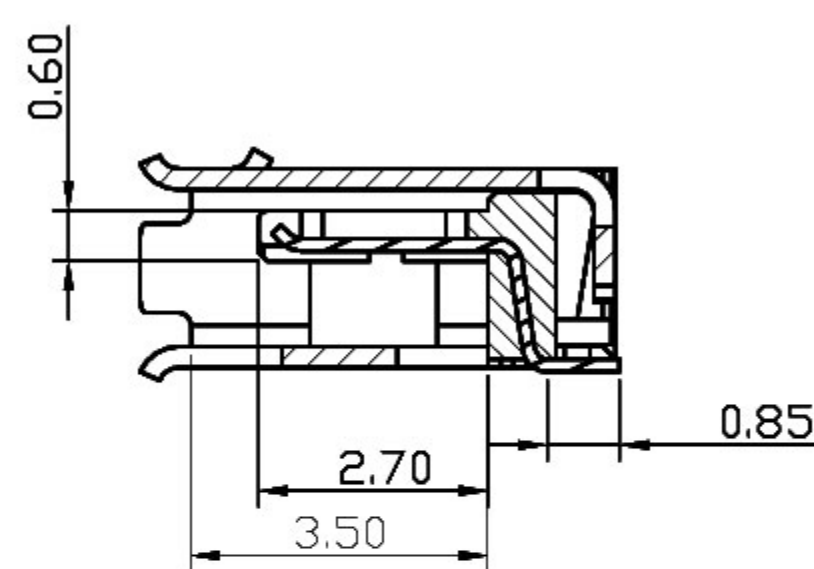
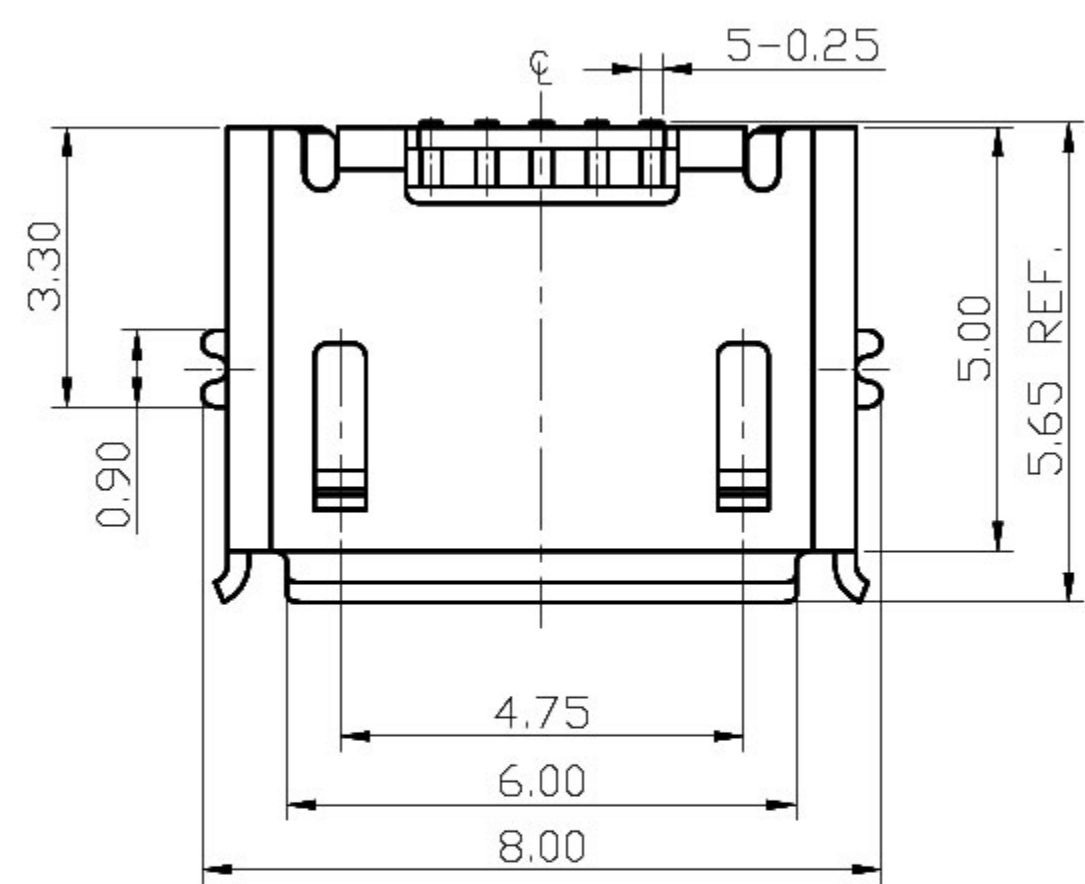
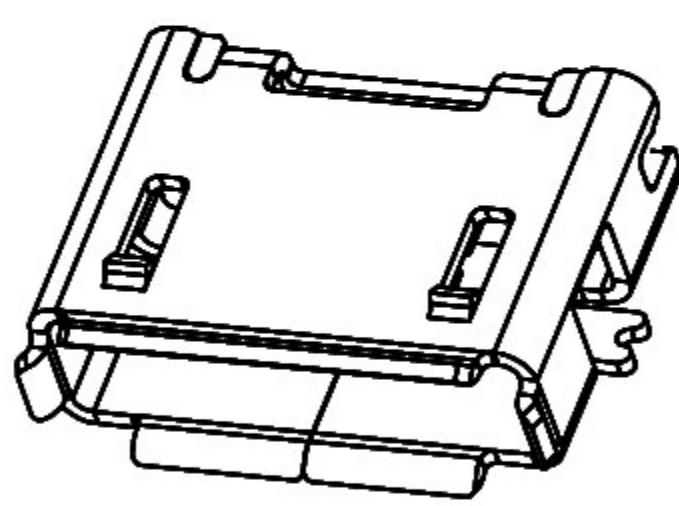
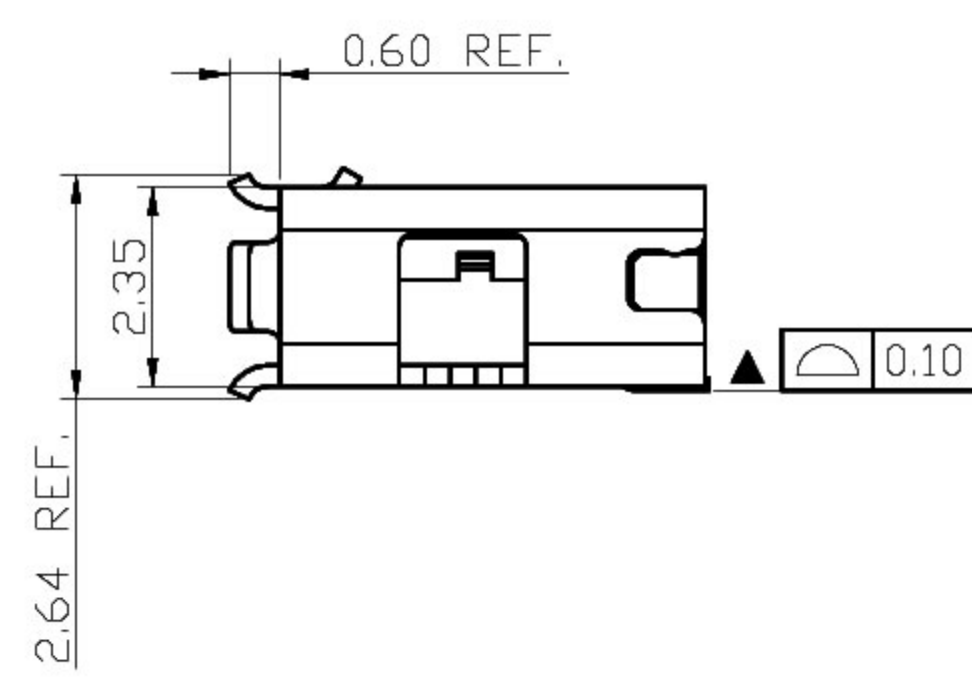
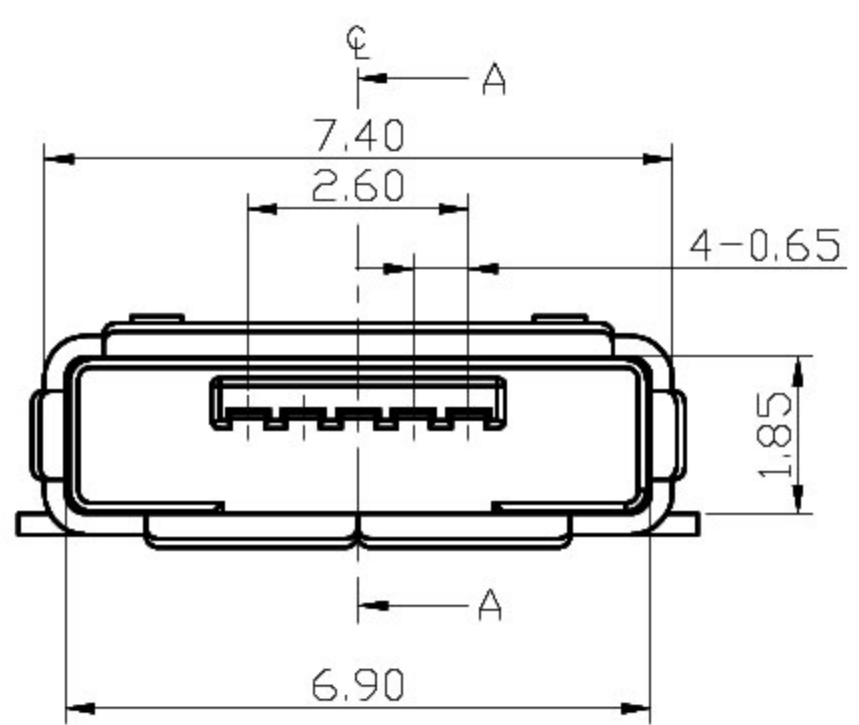


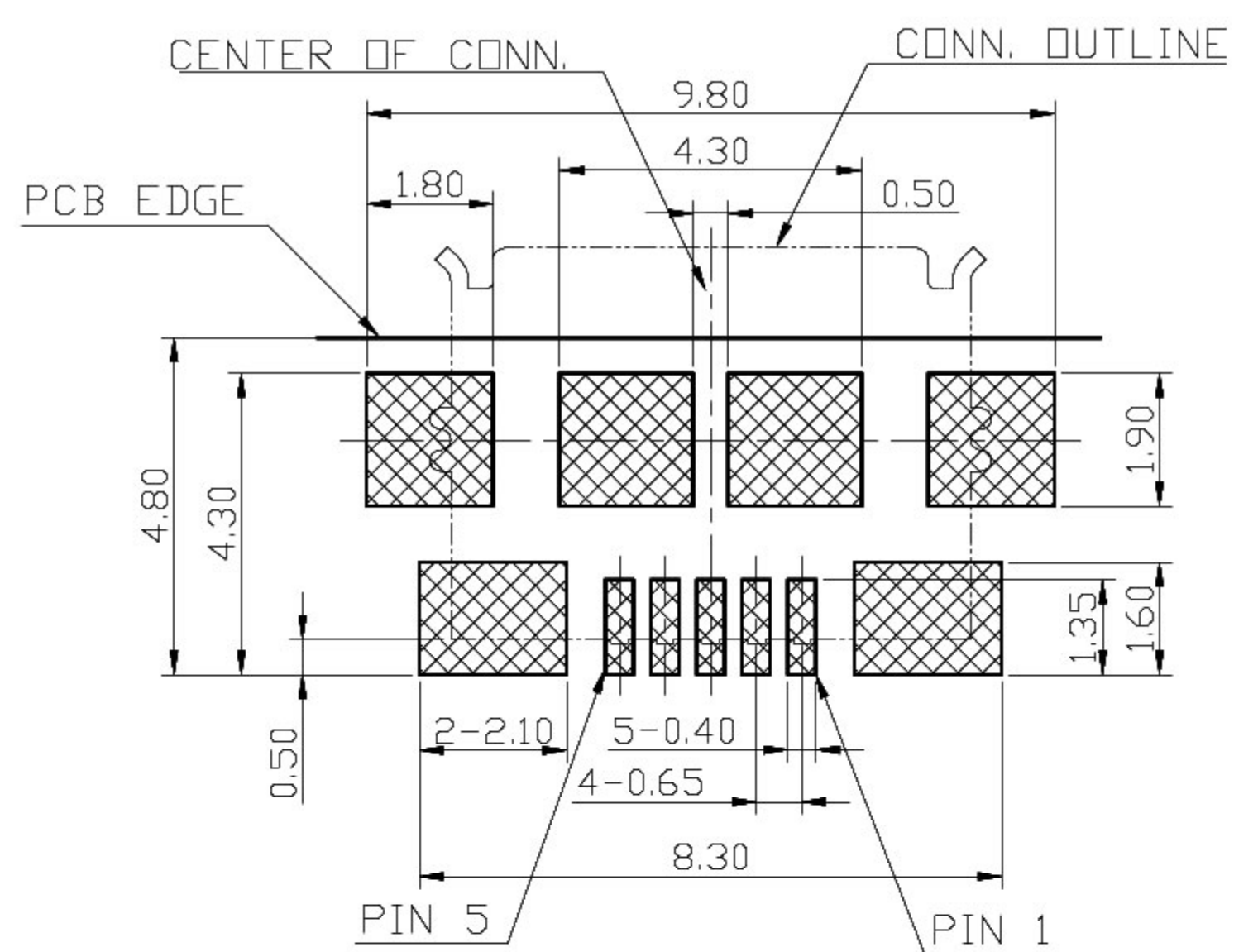
版次	設變內容	設變編號	日期	修改	核准
1-0	NEW RELEASE	ECN090411	2009 04/21	BESS	TDM
1-1	修正電鍍膜厚	ECN090905	2009 09/04	BESS	TDM



SECTION A-A



NOTES:
 1. MATERIAL :
 TERMINAL : COPPER ALLOY,
 HOUSING : THERMOPLASTIC,COLOR IN BLACK , UL94V-0
 SHELL: INFORMATION REFER TO TABLE
 2. FINISH :
 TERMINAL:
 UNDERPLATING: NICKEL PLATING FOR ALL 80U" MIN.
 SOLDER TAIL PLATING: TINKLEAD FREE) PLATING 80U" MIN.
 CONTACT AREA IS PLATED GOLD,INFORMATION REFER TO TABLE
 SHELL:
 UNDERPLATING: NICKEL PLATING FOR ALL 50U" MIN.
 SOLDER TAIL PLATING: TINKLEAD FREE) PLATING 80U" MIN.
 3. PACKAGING : TAPE & REEL,
 REFER TO 17200-005XX-PK
 4. PRODUCT SPECIFICATION :
 REFER TO 17200-PS
 5. PART NUMBER : 17200-005XX-C



RECOMMEND P.C.B. LAYOUT
 GENERAL TOLERANCE: ±0.05
 ☒ SOLDER PAD AREA

一般公差	
X	±---
X.X	±.25
X.XX	±0.20
X.XXX	±---

圖名	MICRO USB CONN. AB RECEPTACLE SMT WITHOUT POST TYPE	單位	mm	
產品編號	AUMCU-17200-00551			
圖號	AUMCU-17200-00551			
日期	2009/09/04	11	1-1	1/1 繪圖

